Product data sheet

1. General description

Hyperfast power diode in a SOD113 (2-lead TO-220F) plastic package.

2. Features and benefits

- · Isolated plastic package
- Low thermal resistance
- · Low reverse recovery current
- Reduces switching losses in associated MOSFET

3. Applications

- Continuous Current Mode (CCM) Power Factor Correction (PFC)
- · Half-bridge/full-bridge switched-mode power supplies
- · Half-bridge lighting ballasts

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Va	lues		Unit
Absolute	maximum rating						
V_{RRM}	repetitive peak reverse voltage		600			V	
$I_{F(AV)}$	average forward current	$δ = 0.5$; square-wave pulse; $T_h \le 41$ °C; Fig. 1; Fig. 2	10			А	
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 μs; T _h ≤ 41 °C; square-wave pulse	20			А	
I _{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 3	65 71			А	
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse				Α	
Symbol	Parameter	Conditions	Min Typ Max		Max	Unit	
Static ch	aracteristics						
V _F	forward voltage	I _F = 10 A; T _j = 25 °C; <u>Fig. 5</u>		-	2	2.5	V
		I _F = 10 A; T _j = 150 °C; <u>Fig. 5</u>		-	1.4	1.8	V
		I _F = 20 A; T _j = 150 °C; <u>Fig. 5</u>		-	1.7	2.2	V
Dynamic	characteristics	'			1	1	
t _{rr}	reverse recovery time	$I_F = 10 \text{ A}$; $V_R = 400 \text{ V}$; $dI_F/dt = 500 \text{ A}/\mu\text{s}$; $T_i = 25 \text{ °C}$; Fig. 6		-	18	-	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	mb	
2	А	anode		K -K -A
mb	n.c.	mounting base; isolated		001aaa020
			SOD113 (2-lead TO-220F)	

6. Ordering information

Table 3. Ordering information

Type number	Package				
	Name	Description	Version		
BYC10DX-600	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 2-lead TO-220 "full pack"	SOD113		

7. Marking

Table 4. Marking codes

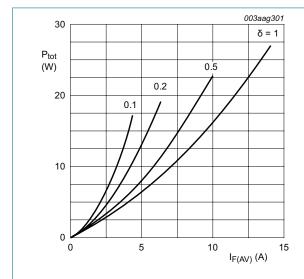
Type number	Marking codes
BYC10DX-600	BYC10DX-600

8. Limiting values

Table 5. Limiting values

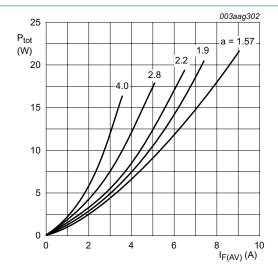
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		600	V
V_{RWM}	crest working reverse voltage		600	V
V_R	reverse voltage	DC	500	V
I _{F(AV)}	average forward current	$δ = 0.5$; square-wave pulse; $T_h \le 41$ °C; Fig. 1; Fig. 2	10	А
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 μs; T _h ≤ 41 °C; square-wave pulse	20	А
I _{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 3	65	А
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse	71	А
T _{stg}	storage temperature		-40 to 150	°C
T _j	junction temperature		150	°C



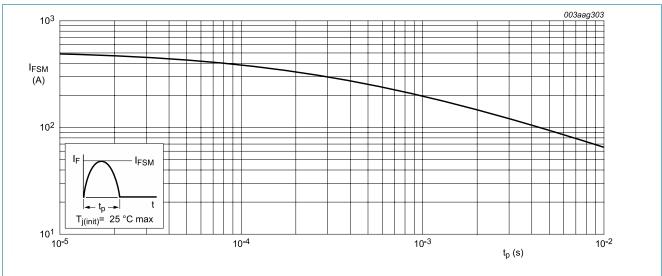
 V_o = 0.987 V; R_s = 0.065 Ω Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

 $I_{\text{F(AV)}} = I_{\text{F(RMS)}} \times \sqrt{\delta}$



a = form factor = $I_{F(RMS)}/I_{F(AV)}$ V_o = 0.987 V; R_s = 0.065 Ω

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values



9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-h)}$	thermal resistance	with heatsink compound; Fig 4	-	-	4.8	K/W
	from junction to heatsink	without heatsink compound	-	-	5.9	K/W
R _{th(j-a)}	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W

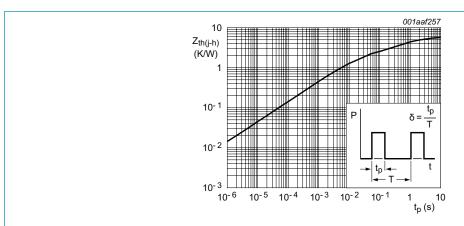


Fig. 4. Transient thermal impedance from junction to heatsink as a function of pulse duration

10. Isolation characteristics

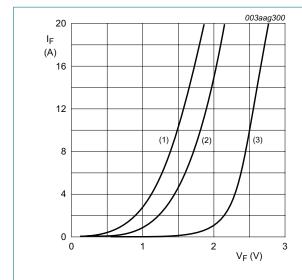
Table 7. Isolation characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{isol(RMS)}	RMS isolation voltage	50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free	-	-	2500	V
C _{isol}	isolation capacitance	f = 1 MHz; from cathode to external heatsink	-	10	-	PF

11. Characteristics

Table 8 Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
V_{F}	forward voltage	I _F = 10 A; T _j = 25 °C; <u>Fig. 5</u>	-	2	2.5	V
		I _F = 10 A; T _j = 150 °C; <u>Fig. 5</u>	-	1.4	1.8	V
		I _F = 20 A; T _j = 150 °C; <u>Fig. 5</u>	-	1.7	2.2	V
I _R reverse current	reverse current	V _R = 600 V; T _j = 25 °C	-	9	200	μA
		V _R = 500 V; T _j = 100 °C	-	1.1	3	mA
Dynamic	characteristics					
t _{rr}	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 6$	-	15	30	ns
		$I_F = 10 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 6$	-	18	-	ns
I _{RM}	peak reverse recovery current	$I_F = 10 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_j = 100 \text{ °C}; Fig. 6$	-	9.5	12	А
		$I_F = 10 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 50 \text{ A/}\mu\text{s};$ $T_j = 125 \text{ °C}; Fig. 6$	-	3	7.5	А
V_{FR}	forward recovery voltage	$I_F = 10 \text{ A}; \text{ dI}_F/\text{dt} = 100 \text{ A/}\mu\text{s};$ $T_i = 25 \text{ °C}; \frac{\text{Fig. 7}}{2}$	-	8	11	V



 V_o = 0.987 V; R_s = 0.065 Ω

(1) T_j = 150 °C; typical values (2) T_j = 150 °C; maximum values

(3) T_i = 25 °C; maximum values

Fig. 5. Forward current as a function of forward voltage

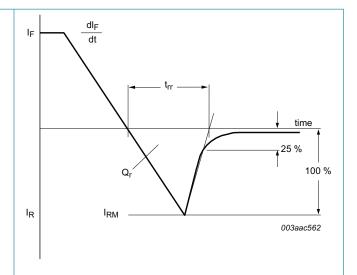
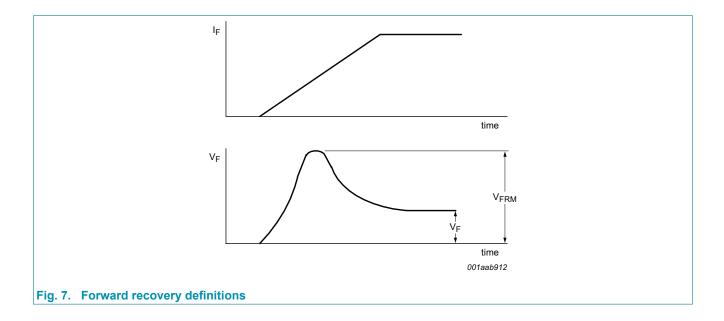
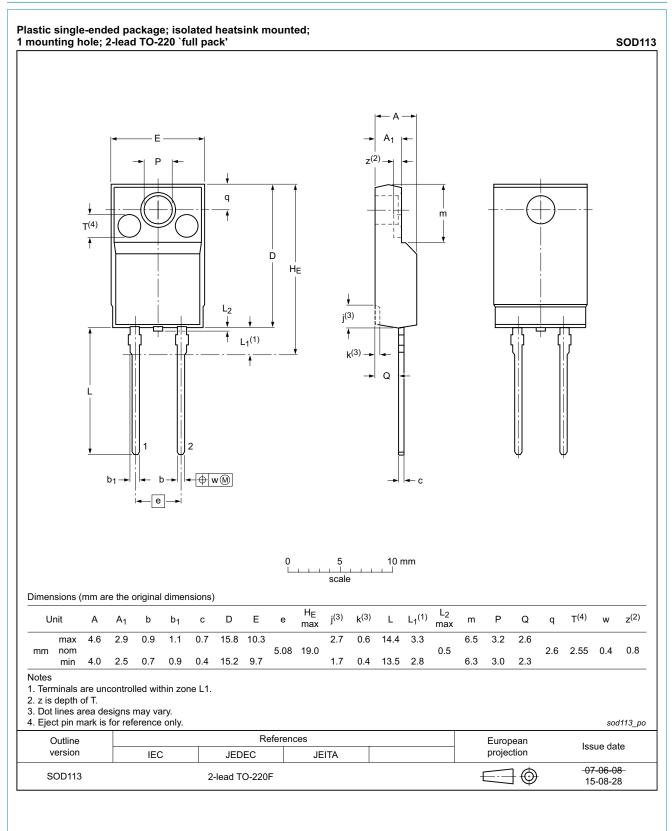


Fig. 6. Reverse recovery definitions; ramp recovery



12. Package outline



13. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes			
BYC10DX-600 v.2	20180926	Product data sheet	-	BYC10DX-600 v.1			
Modifications:	Change from NXP version to WeEn version						
BYC10DX-600 v.1	20110630	Product data sheet	-	-			

14. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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